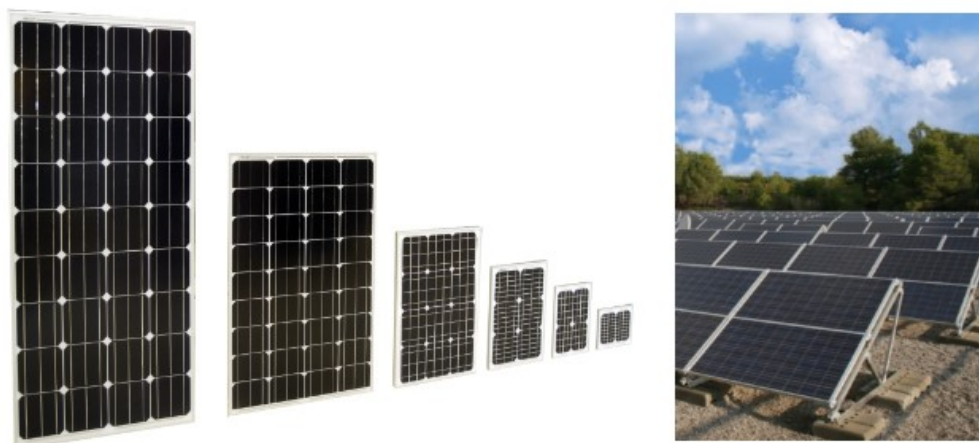


ANEXO I (Módulo Solar)

TECHNO SUN

Módulo fotovoltaicos Techno Sun
5 / 10 / 20 / 40 / 100 / 150W



Módulos FV monocristalinos Techno Sun de alto rendimiento

Descripción

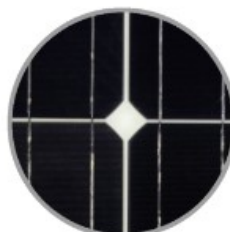
La gama de paneles solares de tecnología monocristalina de Techno Sun cuenta con una alta eficiencia de hasta el 17,96% de célula* y 15,92% del módulo*, tolerancia del $\pm 3\%$ y alta calidad de fabricación para proporcionar el mejor rendimiento.

Características destacadas

- » Células solares de alta eficiencia con transmisión y cristal texturizado .
- » Diodo de bypass para minimizar las pérdidas por sombras.
- » Vidrio templado con encapsulado EVA y película de protección frente al medio ambiente, con marco de aluminio.
- » Cumple las certificaciones internacionales (CE, TÜV NORD, ISO) y está incluido en el programa PV Cycle.

Aplicaciones

Sistemas de energía solar fotovoltaica para aplicaciones residenciales, comerciales o industriales aisladas de la red, de energía de respaldo o conectadas a red .



* Valores de referencia del modelo de 150W, consultar tabla de valores para cada modelo.



Datos eléctricos						
Potencia máxima (W)	5	10	20	40	100	150
Tensión de potencia óptima (Vmp)	18,57	18,57	17,82	17,69	18,78	18,99
Corriente operativa óptima (Imp)	0,27	0,54	1,12	2,26	5,32	7,90
Tensión de circuito abierto (Voc)	22,64	22,64	22,54	22,54	22,64	22,42
Corriente de cortocircuito (Isc)	0,29	0,58	1,20	2,42	5,70	8,45
Eficiencia de célula (%)	17,96	17,96	16,76	16,56	17,88	17,96
Eficiencia de módulo (%)	9,16	10,83	11,45	12,74	14,90	15,12
Tolerancia (%)	±3%	±3%	±3%	±3%	±3%	±3%
NOCT	47°C +/-2°C	47°C +/-2°C	47°C +/-2°C	47°C +/-2°C	47°C +/-2°C	47°C +/-2°C

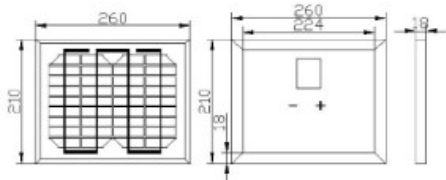
Coef. de temperatura						
Coef. de temperatura Isc (%/°C)	+0.04	+0.04	+0.04	+0.04	+0.04	+0.04
Coef. de temperatura Voc (%/°C)	-0.38	-0.38	-0.38	-0.38	-0.38	-0.38
Coef. de temperatura Pm (%/°C)	-0.47	-0.47	-0.47	-0.47	-0.47	-0.47
Coef. de temperatura Im (%/°C)	+0.04	+0.04	+0.04	+0.04	+0.04	+0.04
Coef. de temperatura Vm (%/°C)	-0.38	-0.38	-0.38	-0.38	-0.38	-0.38

Datos mecánicos						
Célula	52*15,3 (16,8)	52*30,6 (32,1)	156*21,9 (23,5)	156*44,3 (45,7)	156*104	156*156
Tecnología de célula	Monocristalina	Monocristalina	Monocristalina	Monocristalina	Monocristalina	Monocristalina
Número de células (pcs)	4*9	4*9	2*18	4*9	4*9	4*9
Tamaño del módulo (mm)	260*210*18	260*355*18	485*360*28	470*668*35	1005*668*35	1485*668*35
Grosor del cristal (mm)	3.2	3.2	3.2	3.2	3.2	3.2
Máx. carga de superficie	2400-5400Pa	2400-5400Pa	2400-5400Pa	2400-5400Pa	2400-5400Pa	2400-5400Pa
Resistencia al granizo	23m/s ,7.53g	23m/s ,7.53g	23m/s ,7.53g	23m/s ,7.53g	23m/s ,7.53g	23m/s ,7.53g
Peso de la unidad (Kg)	0,7	1,2	2,3	3,8	8	11,6
Corriente máxima del fusible (A)	-	-	-	10	10	10
Marco	18#	18#	28#	28#	35#	35#
Tipo de conector	MC4	MC4	MC4	MC4	MC4	MC4
Parte posterior	TPT	TPT	TPT	TPT	TPT	TPT
Rango de temperatura	-40°C / +85°C	-40°C / +85°C	-40°C / +85°C	-40°C / +85°C	-40°C / +85°C	-40°C / +85°C
FF (%)	70-76%	70-76%	70-76%	70-76%	70-76%	70-76%
Standard Test Conditions	AM1.5 1000W/m² 25°C					

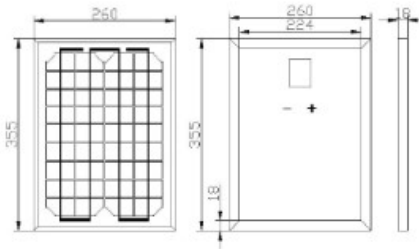
TECHNO SUN

Módulo fotovoltaicos Techno Sun 5 / 10 / 20 / 40 / 100 / 150W

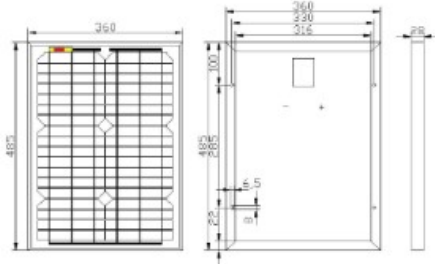
Panel solar 5W



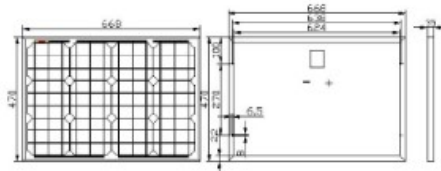
Panel solar 10W



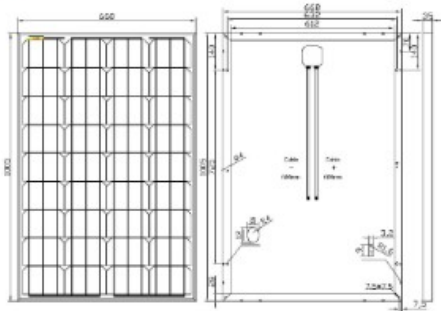
Panel solar 20W



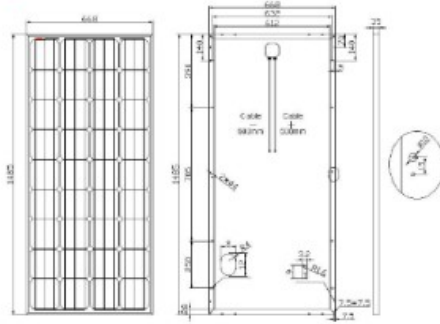
Panel solar 40W



Panel solar 100W



Panel solar 150W



ANEXO II (Componentes Buck)

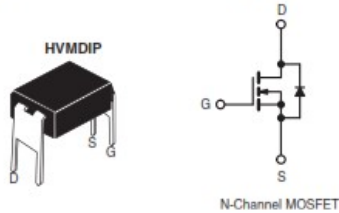


IRFD123, SiHFD123

Vishay Siliconix

Power MOSFET

PRODUCT SUMMARY	
V _{DS} (V)	100
R _{DS(on)} (Ω)	V _{GS} = 10 V 0.27
Q _d (Max.) (nC)	16
Q _{gs} (nC)	4.4
Q _{gd} (nC)	7.7
Configuration	Single



FEATURES

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- For Automatic Insertion
- End Stackable
- 175 °C Operating Temperature
- Fast Switching
- Ease of Paralleling
- Compliant to RoHS Directive 2002/95/EC



DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The 4 pin DIP package is a low cost machine-insertable case style which can be stacked in multiple combinations on standard 0.1" pin centers. The dual drain serves as a thermal link to the mounting surface for power dissipation levels up to 1 W.

ORDERING INFORMATION	
Package	HVMDIP
Lead (Pb)-free	IRFD123PbF SiHFD123-E3
SnPb	IRFD123 SiHFD123

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	± 20	
Continuous Drain Current	V _{GS} at 10 V	T _A = 25 °C	1.3
		T _A = 100 °C	0.94
Pulsed Drain Current ^a	I _{DM}	10	A
Linear Derating Factor		0.0083	W/°C
Single Pulse Avalanche Energy ^b	E _{AS}	100	mJ
Repetitive Avalanche Current ^a	I _{AR}	1.3	A
Repetitive Avalanche Energy ^a	E _{AR}	0.13	mJ
Maximum Power Dissipation	P _D	1.3	W
Peak Diode Recovery dV/dt ^c	dV/dt	5.5	V/ns
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to + 175	°C
Soldering Recommendations (Peak Temperature)	for 10 s	300 ^d	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- V_{DD} = 25 V, starting T_J = 25 °C, L = 22 mH, R_θ = 25 Ω, I_{AS} = 2.6 A (see fig. 12).
- I_{SD} ≤ 9.2 A, di/dt ≤ 110 A/μs, V_{DD} ≤ V_{DS}, T_J ≤ 175 °C.
- 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply



IRFD123, SiHFD123

Vishay Siliconix



THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{\theta JA}$	-	120	$^{\circ}\text{C}/\text{W}$

SPECIFICATIONS ($T_J = 25^{\circ}\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	100	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25^{\circ}\text{C}, I_D = 1\ \text{mA}$	-	0.13	-	$\text{V}/^{\circ}\text{C}$
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	2.0	-	4.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20\ \text{V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 100\ \text{V}, V_{GS} = 0\ \text{V}$	-	-	25	μA
		$V_{DS} = 80\ \text{V}, V_{GS} = 0\ \text{V}, T_J = 150^{\circ}\text{C}$	-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\ \text{V}, I_D = 0.78\ \text{A}^b$	-	-	0.27	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 50\ \text{V}, I_D = 0.78\ \text{A}^b$	0.80	-	-	S

Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0\ \text{V}$ $V_{DS} = 25\ \text{V}$ $f = 1.0\ \text{MHz}$, see fig. 5	-	360	-	pF
Output Capacitance	C_{oss}		-	150	-	
Reverse Transfer Capacitance	C_{rss}		-	34	-	
Total Gate Charge	Q_g	$V_{GS} = 10\ \text{V}$ $I_D = 9.2\ \text{A}, V_{DS} = 80\ \text{V}$ see fig. 6 and 13 ^b	-	-	16	nC
Gate-Source Charge	Q_{gs}		-	-	4.4	
Gate-Drain Charge	Q_{gd}		-	-	7.7	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 50\ \text{V}, I_D = 9.2\ \text{A}$ $R_{\theta} = 18\ \Omega, R_D = 5.2\ \Omega$, see fig. 10 ^b	-	6.8	-	ns
Rise Time	t_r		-	27	-	
Turn-Off Delay Time	$t_{d(off)}$		-	18	-	
Fall Time	t_f		-	17	-	
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact 	-	4.0	-	nH
Internal Source Inductance	L_S		-	6.0	-	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	1.3	A
Pulsed Diode Forward Current ^a	I_{SM}		-	-	10	
Body Diode Voltage	V_{SD}	$T_J = 25^{\circ}\text{C}, I_S = 1.3\ \text{A}, V_{GS} = 0\ \text{V}^b$	-	-	2.5	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25^{\circ}\text{C}, I_F = 9.2\ \text{A}, di/dt = 100\ \text{A}/\mu\text{s}^b$	-	130	260	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	0.65	1.3	
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\ \mu\text{s}$; duty cycle $\leq 2\ \%$.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

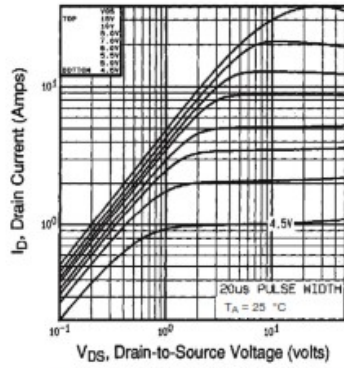


Fig. 1 - Typical Output Characteristics, $T_A = 25\text{ }^\circ\text{C}$

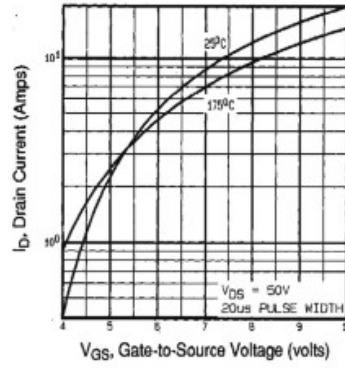


Fig. 3 - Typical Transfer Characteristics

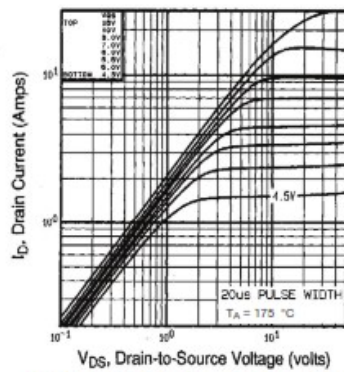


Fig. 2 - Typical Output Characteristics, $T_A = 175\text{ }^\circ\text{C}$

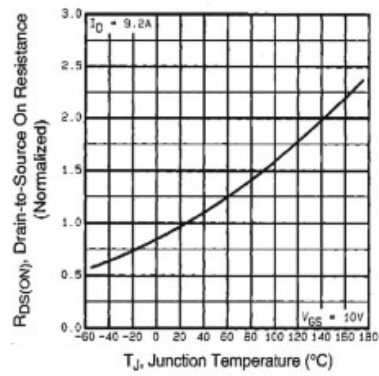


Fig. 4 - Normalized On-Resistance vs. Temperature

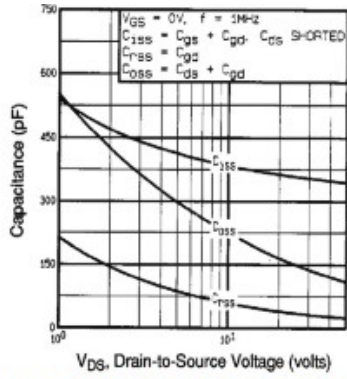


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

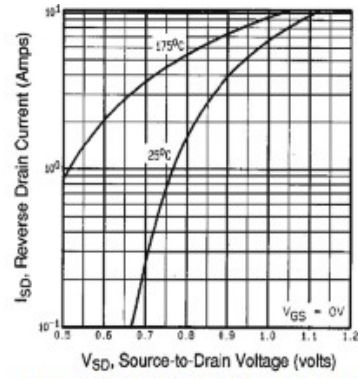


Fig. 7 - Typical Source-Drain Diode Forward Voltage

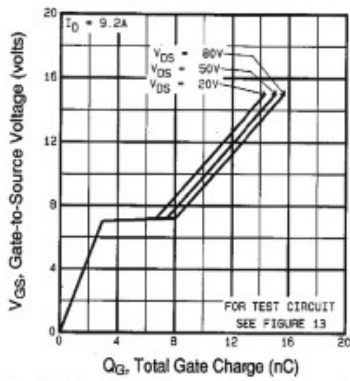


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

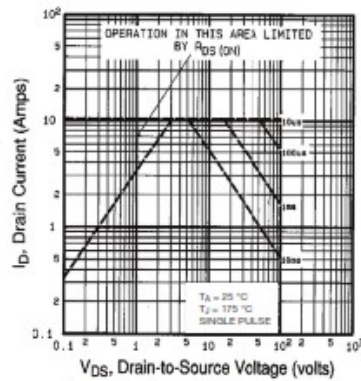
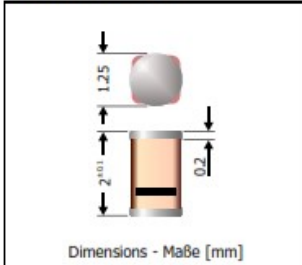


Fig. 8 - Maximum Safe Operating Area

MCL103B, MCL103C
Surface Mount Small Signal Diodes
Kleinsignal-Dioden für die Oberflächenmontage

Version 2006-10-30

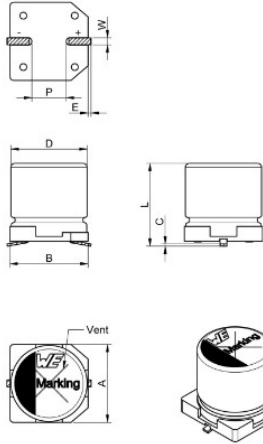


Power dissipation Verlustleistung	400 mW
Repetitive peak reverse voltage Periodische Spitzenspannung	20...30 V
Glass case Quadro-MicroMELF Glasgehäuse Quadro-MicroMELF	(LS-31)
Weight approx. – Gewicht ca.	0.01 g
Standard packaging taped and reeled Standard Lieferform gegurtet auf Rolle	

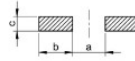
**Maximum ratings and characteristics****Grenz- und Kennwerte**

		MCL103B	MCL103C
Repetitive peak reverse voltage Periodische Spitzenspannung	V_{RRM}	30 V	20 V
Leakage current, $T_J = 25^\circ\text{C}$ Sperrstrom, $T_J = 25^\circ\text{C}$	$V_R = 20\text{ V}$	$I_R = 5\ \mu\text{A}$	–
	$V_R = 10\text{ V}$	–	$5\ \mu\text{A}$
Forward voltage, $T_J = 25^\circ\text{C}$ Durchlass-Spannung, $T_J = 25^\circ\text{C}$	$I_F = 20\text{ mA}$	$V_F < 0.37\text{ V}$	
	$I_F = 200\text{ mA}$	$V_F < 0.6\text{ V}$	
Power dissipation – Verlustleistung	$T_A = 25^\circ\text{C}$	P_{tot}	400 mW ¹⁾
Peak forward surge current, 10 μs square pulse Stoßstrom für einen 10 μs Rechteckimpuls	$T_A = 25^\circ\text{C}$	I_{FSM}	15 A
Max. junction capacitance – Max. Sperrschichtkapazität $V_R = 0\text{ V}$, $f = 1\text{ MHz}$		C_j	typ. 50 pF
Reverse recovery time – Sperrverzögerung $I_F = 200\text{ mA}$ über/through $I_R = 200\text{ mA}$ bis/to $I_R = 20\text{ mA}$		t_{rr}	typ. 10 ns
Junction temperature – Sperrschichttemperatur Storage temperature – Lagerungstemperatur	T_J		-55...+175°C
	T_S		-55...+175°C
Thermal resistance junction to ambient air Wärmewiderstand Sperrschicht – umgebende Luft		R_{thA}	< 300 K/W ¹⁾

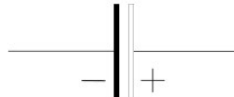
A Dimensions: [mm]



B Recommended hole pattern: [mm]



C Schematic:



D1 Electrical Properties:

Properties	Test conditions	C	Value	Unit	Tol.
Capacitance	0.25V, 120Hz	C	27	μF	$\pm 20\%$
Rated voltage		U_{R1}	25	V (DC)	max.
Leakage current	after 2 min.	$I_{L, \text{peak}}$	6.75	μA	max.
Dispipation factor	120 Hz	DF	14	%	typ.
Ripple current	100kHz @105°C	I_{ripple}	200	mA	max.
Impedance	100kHz @20°C	Z	0.62	Ω	max.

E General information:

Aluminium Electrolytic Capacitors
 Storage Conditions: 35°C, $\pm 45\% \text{ RH}$
 Operating Temperature: -55 °C up to +105 °C
 Lead Life: 2000 h @ +105°C / 25 V (DC)
 Test conditions of Electrical Properties: 20°C, 33% RH; if not specified differently
 FIT according to separate documentation

L max.	5.5		
D ± 0.5	6.3		
A ± 0.2	6.6		
B ± 0.2	6.6		
C max.	0.15		
W ± 0.1	0.65	a	2.1
E ± 0.05	0.35	b	3.5
P ± 0.2	2.2	c	1.6

REV	DATE	BY	CHECKED
1.0	2014-11-11	SS	PS

DESCRIPTION	
WCAP-ASLI Aluminum Electrolytic Capacitors	
Order No:	865080443005
Size:	6.3 x 5.5
COMPLIANT	RoHS&REACH
	S2E
	A4

This electronic component has been designed and developed for usage in general electronic equipment only. This product is not authorized for use in equipment where a higher safety standard and reliability standard is especially required or where a failure of the product is reasonably expected to cause severe personal injury or death, unless the parties have concluded an agreement specifically governing such use. Moreover Würth Elektronik eGmbH & Co KG products are neither designed nor intended for use in areas such as military, aerospace, aviation, nuclear control, submarine, transportation (automotive control, train control, ship control), temperature signal, disaster prevention, medical, public information network etc. Würth Elektronik eGmbH & Co KG must be informed about the intent of such usage before the design-in stage. In addition, sufficient reliability evaluation checks for safety must be performed on every electronic component which is used in electrical circuits that require high safety and reliability functions or performance.

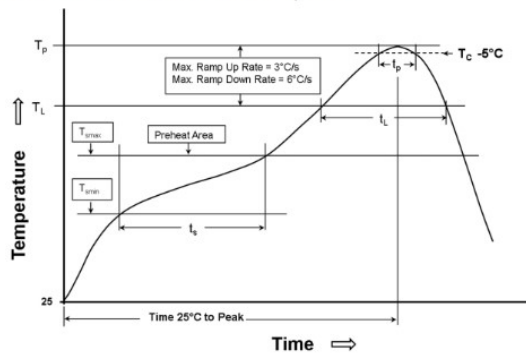
Component Marking:

Print	Description
1 st Line	Capacitance value: 27 μF
2 nd Line	Rated Voltage: 25
3 rd Line	WCAP-ASLI & datecode: YWW

D2 Multiplier for Ripple Current vs. Frequency:

C [μF] / Frequency [Hz]	60 (50)	120	400	1000	10000	50000-100000
C ≤ 10	0.47	0.59	0.76	0.85	0.97	1.00
10 < C	0.52	0.65	0.80	0.85	0.97	1.00

H1: Classification Reflow Profile for SMT components:



H2: Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Preheat	150°C
- Temperature Min (T_{preheat})	200°C
- Temperature Max (T_{preheat})	60-120 seconds
- Time (t_p) from (T_{preheat} to T_{max})	3°C/second max.
Ramp-up rate (T_L to T_p)	217°C
Liquidous temperature (T_L)	60-150 seconds
Time (t_L) maintained above T_L	See Table H3
Peak package body temperature (T_p)	20-30 seconds
Time within 5°C of actual peak temperature (t_p)	6°C/second max.
Ramp-down rate (T_p to T_L)	8 minutes max.
Time 25°C to peak temperature	

refer to IPC/JEDEC J-STD-020D

H3: Package Classification Reflow Temperature

	Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
Pb-Free Assembly	< 1.6 mm	260°C	260°C	260°C
Pb-Free Assembly	1.6 - 2.5 mm	260°C	250°C	245°C
Pb-Free Assembly	≥ 2.5 mm	250°C	245°C	245°C

refer to IPC/JEDEC J-STD-020D

ANEXO III (Buck + ACC)

Buck ACC.xmcd

Módulo BP 4165. Condiciones de trabajo: $T_a = 34^\circ\text{C}$, $G = 70 \text{ mW/cm}^2$

Datos:

Carga: $R_L := 6\Omega$

$$e_e := 1.602 \cdot 10^{-19} \text{ C}$$

$$m_m := 1$$

$$k := 1.381 \cdot 10^{-23} \text{ J}\cdot\text{K}^{-1}$$

$$V_t := 0.026 \text{ V}$$

Condiciones estándar: $T_a := 25$ $G_{\text{STC}} := 1 \frac{\text{kW}}{\text{m}^2}$

Condiciones de trabajo: $G_{\text{ct}} := 700 \frac{\text{W}}{\text{m}^2}$ $T_{a_ct} := 34$ $T_{\text{ct}} := (273 + T_{a_ct})\text{K}$

Datos módulos (STC):

$$P_{\text{M_MOD}} := 5 \text{ W}$$

$$V_{\text{M_MOD_STC}} := 18.57 \text{ V}$$

$$I_{\text{M_MOD_STC}} := 0.54 \text{ A}$$

$$V_{\text{OC_MOD_STC}} := 22.64 \text{ V}$$

$$I_{\text{SC_MOD_STC}} := 0.58 \text{ A}$$

$$\text{NOCT} := 47$$

$$N_{\text{S_MOD}} := 36$$

$$N_{\text{P_MOD}} := 1$$

$$K_{\text{OC_T}} := -0.38 \text{ mV}$$

Coefficiente de temperatura de Voc de las células

Células:

$$R_{\text{S_MOD}} := \frac{(V_{\text{OC_MOD_STC}} - V_{\text{M_MOD_STC}})}{I_{\text{M_MOD_STC}}} = 7.537 \Omega$$

a) Punto de funcionamiento del módulo en condiciones de trabajo:

$$C_1 := \frac{I_{\text{SC_MOD_STC}}}{100 \frac{\text{mW}}{\text{cm}^2}}$$

$$C_1 = 5.8 \times 10^{-3} \cdot \frac{\text{A}\cdot\text{cm}^2}{\text{mW}}$$

$$I_{\text{SC_MOD}} := C_1 \cdot G_{\text{ct}}$$

$$I_{\text{SC_MOD}} = 0.406 \text{ A}$$

$$C_2 := \frac{\text{NOCT} - 20}{80 \frac{\text{mW}}{\text{cm}^2}}$$

$$C_2 = 0.0338 \cdot \frac{\text{m}^2}{\text{W}}$$

$$e^1 = 2.718$$

En condiciones estándar:

$$T_{\text{c_STC}} := 25 + C_2 \cdot G_{\text{STC}}$$

$$T_{\text{c_STC}} = 58.75^\circ\text{C}$$

En las condiciones de trabajo:

$$T_{\text{c}} := T_{a_ct} + C_2 \cdot G_{\text{ct}}$$

$$T_{\text{c}} = 57.625^\circ\text{C}$$

$$V_{\text{OC_MOD}} := V_{\text{OC_MOD_STC}} + K_{\text{OC_T}} \cdot (T_{\text{c}} - T_{\text{c_STC}}) \cdot N_{\text{S_MOD}}$$

$$V_{\text{OC_MOD}} = 22.655 \text{ V}$$

b) Punto de funcionamiento del módulo sin MPPT:

$$I_{MOD}(V_{MOD}) := I_{SC_MOD} \cdot \left(1 - e^{-\frac{V_{MOD} - V_{OC_MOD} + I_{SC_MOD} \cdot R_{S_MOD}}{N_{S_MOD} \cdot V_t}} \right)$$

$$V_R := 5V$$

$$I_{MOD_Q} := I_{SC_MOD} \cdot \left(1 - e^{-\frac{V_R - V_{OC_MOD} + I_{SC_MOD} \cdot R_{S_MOD}}{N_{S_MOD} \cdot V_t}} \right) = 0.406A$$

$$V_{MOD_Q} := V_R$$

$$P_{MOD_Q} := V_{MOD_Q} \cdot I_{MOD_Q} = 2.03W$$

c) Punto de máxima potencia del módulo:

$$P_{MOD}(V_{MOD}) := I_{MOD}(V_{MOD}) \cdot V_{MOD}$$

$$\frac{d}{dV_{MOD}} P_{MOD}(V_{MOD}) = I_{MOD}(V_{MOD}) + \frac{d}{dV_{MOD}} I_{MOD}(V_{MOD}) \cdot V_{MOD}$$

$$0 = I_{SC_MOD} - \left(I_{SC_MOD} + \frac{V_{M_MOD} \cdot I_{SC_MOD}}{N_{S_MOD} \cdot V_t} \right) \cdot e^{-\frac{V_{M_MOD} - V_{OC_MOD} + I_{SC_MOD} \cdot R_{S_MOD}}{N_{S_MOD} \cdot V_t}}$$

Giver

$$V_{M_MOD} := 2V$$

$$0 = I_{SC_MOD} - \left(I_{SC_MOD} + \frac{V_{M_MOD} \cdot I_{SC_MOD}}{N_{S_MOD} \cdot V_t} \right) \cdot e^{-\frac{V_{M_MOD} - V_{OC_MOD} + I_{SC_MOD} \cdot R_{S_MOD}}{N_{S_MOD} \cdot V_t}}$$

$$V_{M_mod} := \text{Find}(V_{M_MOD})$$

$$V_{M_MOD} := V_{M_mod}$$

$$V_{M_MOD} = 16.84V$$

$$I_{M_MOD} := I_{MOD}(V_{M_mod})$$

$$I_{M_MOD} = 0.385A$$

$$P_{M_MOD} := I_{M_MOD} \cdot V_{M_MOD}$$

$$P_{M_MOD} = 6.477W$$

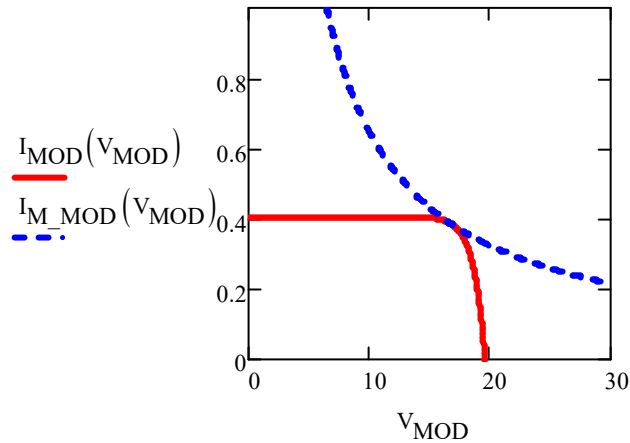
$$I_R := \frac{P_{M_MOD}}{5V} = 1.295A$$

d) Con MPPT (ideal):

- Punto de funcionamiento del módulo: Punto de máxima potencia

Hipérbola de potencia constante (= máxima):

$$I_{M_MOD}(V_{MOD}) \cdot V_{MOD} = P_{M_MOD} \qquad I_{M_MOD}(V_{MOD}) := \frac{P_{M_MOD}}{V_{MOD}}$$



$$V_{M_MOD} = 16.84V$$

$$I_{MOD}(V_{M_MOD}) = 0.385A$$

$$P_{MOD}(V_{M_MOD}) = 6.477W$$

- Convertidor (ideal): $V_R < V_{MOD}$: Reductor

$$V_o := 5V$$

$$V_R = \delta \cdot V_{M_MOD} \qquad \delta := \frac{V_R}{V_{M_MOD}} \qquad \delta = 0.297$$

$$I_o := \frac{P_{MOD}(V_{M_MOD})}{V_o} = 1.295A$$

Convertidor Buck:

$$V_i := V_{M_MOD} \qquad D := 0.297 \qquad f_s := 50kHz$$

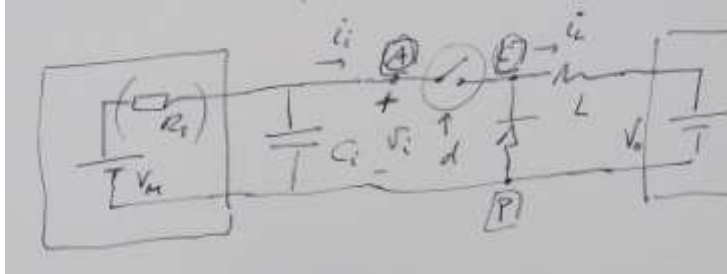
$$L := 372\mu H \qquad R_C := 0.1\Omega \qquad C := 25\mu F$$

$$(0 < t < DT_c) \qquad V_{in} - V_o = L \cdot \frac{di}{dt}$$

Control modo corriente media ACC:

Consideraciones:

- Modelo del módulo fotovoltaico: Fuente de tensión continua de valor V_{M_MOD}
- Modelo de la batería: Fuente de tensión continua $V_o = 5\text{ V}$
- Condensador C_i entre el módulo y la entrada del buck
- Rendimiento del buck = 1



Especificaciones: $f_c < 0.1 - 0.2 f_s$ $f_{ci} := 10\text{kHz}$ $MF_i := 75^\circ$

$$V_m := 0.33\text{V}$$

$$\omega_{ci} := 2 \cdot \pi \cdot f_{ci} = 62.832 \frac{\text{krad}}{\text{s}}$$

$$F_m := \frac{1}{V_m} = 3.03 \frac{1}{\text{V}}$$

DC) $\frac{1}{D} = \frac{V_{M_MOD}}{V_o}$

$$D := \frac{V_o}{V_{M_MOD}} = 0.297$$

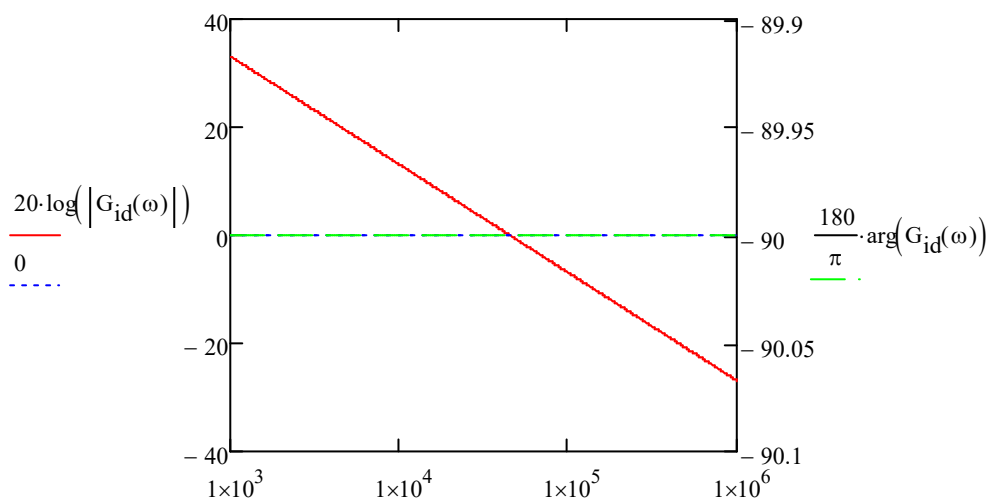
$$\frac{1}{D} = \frac{I_o}{I_i}$$

$$I_i := I_{MOD}(V_{M_MOD}) = 0.385\text{A}$$

$$I_{M_A} := \frac{I_i}{D} = 1.295\text{A}$$

ac) $G_{id}(\omega) = \frac{i_L}{d}$ $v_i = i'_o = 0$

$$d \cdot V_{M_MOD} = j \cdot L \cdot \omega \cdot i_L \quad G_{id}(\omega) := \frac{V_{M_MOD}}{(j \cdot L \cdot \omega)}$$



$$\arg(G_{id}(\omega_{ci})) = -90^\circ$$

Compensador de tipo 2

$$G_I(\omega) = \frac{\omega_{p0c}}{j \cdot \omega} \cdot \frac{1 + j \cdot \frac{\omega}{\omega_{zc}}}{1 + j \cdot \frac{\omega}{\omega_{pc}}}$$

$$\arg(G_{id}(\omega_{ci})) - 90^\circ + AUFA_i = -180^\circ + MF_i$$

$$AUFA_i := -180^\circ + MF_i - (\arg(G_{id}(\omega_{ci})) - 90^\circ) = 75^\circ$$

$$K := \tan\left(\frac{AUFA_i}{2} + 45^\circ\right) = 7.596$$

$$\omega_{zc} := \frac{\omega_{ci}}{K} = 8.272 \frac{\text{krad}}{\text{s}}$$

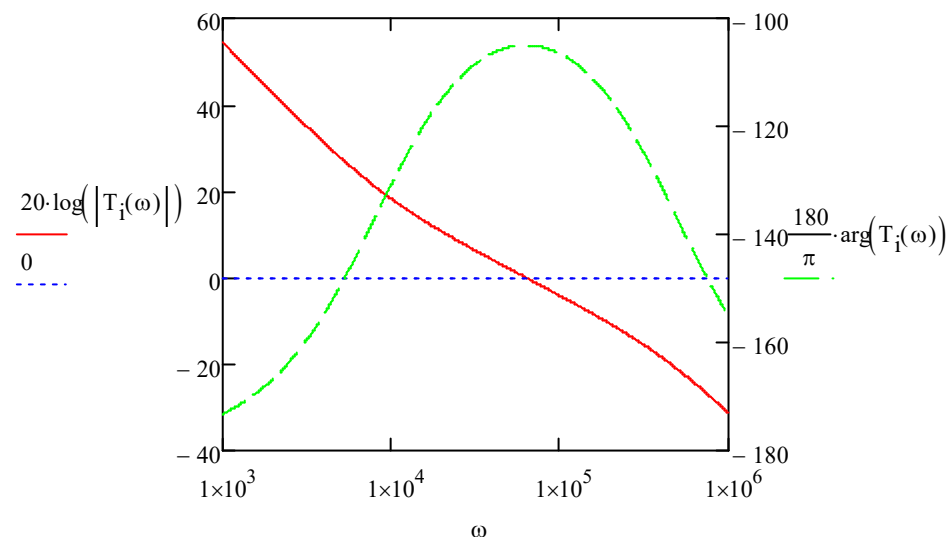
$$\omega_{pc} := \omega_{ci} \cdot K = 477.255 \frac{\text{krad}}{\text{s}}$$

$$|G_{id}(\omega_{ci})| \cdot \frac{\omega_{p0c}}{|\omega_{ci}|} \cdot \frac{\left|1 + j \cdot \frac{\omega_{ci}}{\omega_{zc}}\right|}{\left|1 + j \cdot \frac{\omega_{ci}}{\omega_{pc}}\right|} \cdot F_m = 1$$

$$\omega_{p0c} := \frac{\left|\frac{j \cdot \omega_{ci}}{\omega_{pc}} + 1\right| \cdot |\omega_{ci}|}{\left|\frac{j \cdot \omega_{ci}}{\omega_{zc}} + 1\right| \cdot |G_{id}(\omega_{ci})| \cdot F_m \cdot \Omega} = 3.789 \frac{\text{krad}}{\text{s}}$$

$$G_I(\omega) := \frac{\omega_{p0c}}{j \cdot \omega} \cdot \frac{1 + j \cdot \frac{\omega}{\omega_{zc}}}{1 + j \cdot \frac{\omega}{\omega_{pc}}}$$

$$T_i(\omega) := G_{id}(\omega) \cdot G_I(\omega) \cdot F_m \cdot \Omega$$



Given $\omega_1 := 1000 \frac{\text{rad}}{\text{s}}$

$$|T_i(\omega_1)| = 1$$

$$f_{ci} := \frac{\text{Find}(\omega_1)}{2\pi} = 10 \cdot \text{kHz}$$

$$MF_i := \arg(T_i(2 \cdot \pi \cdot f_{ci})) + 180^\circ = 75^\circ$$

Por tanto, confirmamos que a la frecuencia de cruce tenemos el MF deseado


```

%Función de transferencia de control de corriente en el inductor

Gid= Vi/Zl ; %%%%

figure(2);
bode(Gid); % Respuesta en frecuencia

%Ganancia del lazo de corriente con regulador Gi = 1:

Ti = Gid*Fm ; %%%%

hold on;
bode(Ti);
grid on;

% Diseño del regulador mediante el método K de Venables %

% Frecuencia de cruce y margen de fase deseados

Fci = 10000 ; %%%% Frecuencia de cruce de Ti
wci = Fci*2*pi ; %%%% " en rad/s
MFi = 75 ; %%%% Margen de fase deseado

% Modulo y fase de Gid a la frecuencia de cruce deseada

[M_wci,F_wci]=bode(Gid,wci); % (El módulo no está en dB)

%Determinación del tipo de regulador a partir de la fase.

if F_wci<(-90) % si la fase está entre -90 y -180 Tipo 3

% Fase_objetivo = -180 + MFi;
%
% AUFA = abs(-90-abs(F_wci)-Fase_objetivo) ;%%% Aumento de fase
necesario
%
% K = tand((AUFA/2)+45) ; %%%% Calculamos el factor K.
% %%%% Ojo la función tan() da la tangente en radianes
% %%%% para trabajar en grados utilizar tand()
%
% y determinamos las frecuencias de polos y ceros
%
% wzi = wci/K ; %%%% Frecuencia de los ceros
%
% wpi = wci*K ; %%%% Frecuencia de los polos
%
% Ki = (wci/(M_wci*Ri*Fm))*(1+(wci/wpi)/(1+(wci/wzi))) ; %%%%
Ganancia del regulador
%
%
% Implementación del regulador
%
% Gi = (Ki/s)*(1+(s/wzi))^2/(1+(s/wpi))^2;

```

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%
%   figure(3);
%   bode(Gi); % Respuesta en frecuencia
%   grid on;

elseif ((F_wci>=-90) && (F_wci<-30)) % Regulador Tipo 2

    Fase_objetivo = -180 + MFi;

    AUFA = +90-F_wci+Fase_objetivo ; %%% Aumento de fase necesario

    K = tand((AUFA/2)+45) ; %%% Calculamos el factor K

    % y determinamos las frecuencias de polos y ceros

    wz_i = wci/K ; %%% Frecuencia de los ceros

    wpi = wci*K ; %%% Frecuencia de los polos

    Ki = wci/(M_wci*Fm)*sqrt(1+(wci/wpi)^2)/sqrt(1+(wci/wz_i)^2) ;
    %%% Ganancia del regulador

    % Implementación del regulador

    Gi = (Ki*(1+(s/wz_i)))/(s*(1+(s/wpi)));

    figure(3);
    bode(Gi); % Respuesta en frecuencia
    grid on;

else % Tipo 1

    %%% No va a ser el caso

end

%Ganancia del lazo de corriente con el regulador calculado:

Ti = Gid*Gi*Fm ; %%%

figure(4);
margin(Ti); % Respuesta en frecuencia con la función margin que ofrece
grid on; % la frecuencia de cruce y el margen de fase.

% FDT del lazo cerrado de corriente

Ti_LC = (Ti/(1+Ti)) ; %%%

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